

ABSTRACT OF THE DISCLOSURE

[0058] Embodiments of the present invention form a weight-compensating/tuning layer on a structure (e.g., a silicon wafer with one or more layers of material (e.g., films)) having variations in its surface topology. The variations in surface topology take the form of thick and thin regions of materials. The weight-compensating/tuning layer includes narrow and wide regions corresponding to the thick and thin regions, respectively.